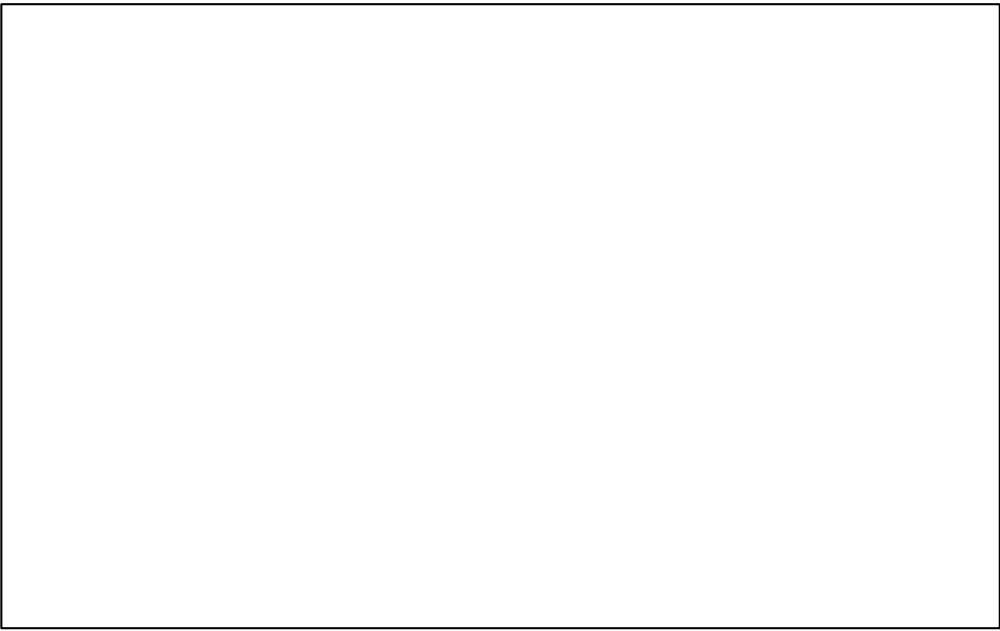


TEXAS INSTRUMENTS		Copper Layer Name			Silkscreen		S Mask		P Mask		Assembly		Drill Drawing
		Top	Internal	Bot	Top	Bot	Top	Bot	Top	Bot	Top	Bot	
Board No.	{Project Number}	Rev.	A										
Date: (Start Date)	Filename: PMP6612A.PCB	Engineer: D.STRASSER	PCB Design: R.SMITH	Modified Date: (Modification Date)	Software: PADS v9.3								



Title (Sheet Date)		Part Name		Project Number		Board No.	
Firmware: PMP101A.PCB		Enterprise: D. STARZGER		A			
PCB Date: R. SMITH			Model Date: (Modification Date)		Revision: P&A 2.3		
Copper Layer Name		Screen 2 Mask		P Mask		Assembly	
Top	Internal	Bot	Top	Bot	Top	Bot	Top Bot
				X		X	BA

Dwg Drawing

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